

Title (en)
LIGHT-EMITTING DIODE PACKAGE ASSEMBLY

Title (de)
LEUCHTDIODENGHÄUSEANORDNUNG

Title (fr)
ENSEMBLE BOÎTIER DE DIODE ÉLECTROLUMINESCENTE

Publication
EP 4033547 A4 20231025 (EN)

Application
EP 20866760 A 20200628

Priority

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- CN 201921554475 U 20190918
- CN 202020278177 U 20200309
- CN 2020098502 W 20200628

Abstract (en)
[origin: US2022199592A1] A light-emitting diode (LED) packaging module includes light-emitting units arranged in an array having m row(s) and n column(s), an encapsulating layer, and a wiring assembly, where m and n each independently represents a positive integer. Each of the light-emitting units includes LED chips each including a chip first surface, a chip second surface, a chip side surface, and an electrode assembly disposed on the chip second surface. The encapsulating layer covers the chip side surface and fills a space among the LED chips. The wiring assembly is disposed on the chip second surface and is electrically connected to the electrode assembly.

IPC 8 full level
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H01L 33/62 (2013.01 - KR US); **H01L 33/486** (2013.01 - EP); **H01L 33/62** (2013.01 - EP)

Citation (search report)

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- [Y] WO 2019045549 A1 20190307 - SEOUL SEMICONDUCTOR CO LTD [KR] & EP 3680932 A1 20200715 - SEOUL SEMICONDUCTOR CO LTD [KR]
- [Y] CN 109216525 A 20190115 - PLAYNITRIDE INC
- [A] US 2018138157 A1 20180517 - IM HYUN DEOK [KR], et al
- See also references of WO 2021051924A1

Designated contracting state (EPC)
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DOCDB simple family (application)
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